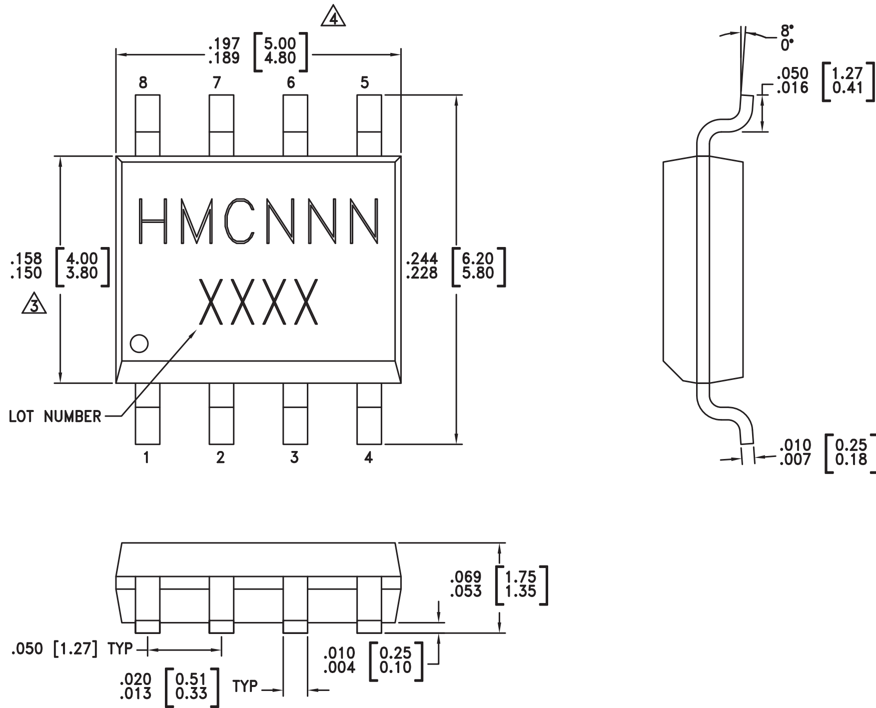
Hittite MICROWAVE CORPORATION v00.0902

S8 (E) – 8 LEAD PLASTIC SOIC PACKAGE

S8 (E) Package Outline Drawing



NOTES:
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

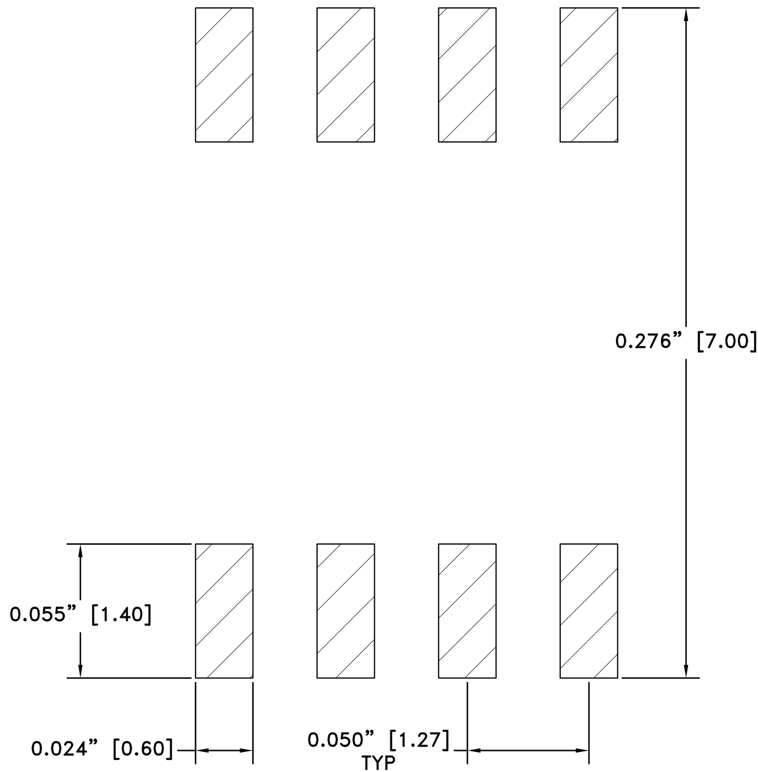
Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking [3][4]
S8	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 [1]	HMCNNN XXXX
S8E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 [2]	HMCNNN XXXX

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX
[4] 3-Digit part number NNN

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
Order On-line at www.hittite.com

Suggested S8 (E) PCB Land Pattern



NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.